

**High Voltage, High Gain
BIMOSFET™**
**IXBH2N250
IXBT2N250**
**Monolithic Bipolar MOS
Transistor**

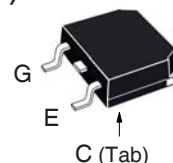

$$V_{CES} = 2500V$$

$$I_{C110} = 2A$$

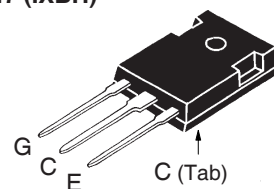
$$V_{CE(sat)} \leq 3.80V$$

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_C = 25^\circ C$ to $150^\circ C$	2500	V
V_{CGR}	$T_J = 25^\circ C$ to $150^\circ C$, $R_{GE} = 1M\Omega$	2500	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ C$	5	A
I_{C110}	$T_C = 110^\circ C$	2	A
I_{CM}	$T_C = 25^\circ C$, 1ms	13	A
SSOA	$V_{GE} = 15V$, $T_{VJ} = 125^\circ C$, $R_G = 47\Omega$	$I_{CM} = 6$	A
(RBSOA)	Clamped Inductive Load	$V_{CE} \leq 2000$	V
P_C	$T_C = 25^\circ C$	32	W
T_J		-55 ... +150	$^\circ C$
T_{JM}		150	$^\circ C$
T_{stg}		-55 ... +150	$^\circ C$
T_L	Maximum Lead Temperature for Soldering	300	$^\circ C$
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	$^\circ C$
M_d	Mounting Torque (TO-247)	1.13 / 10	Nm/lb.in
Weight	TO-247	6	g
	TO-268	4	g

TO-268 (IXBT)



TO-247 (IXBH)



G = Gate D = Drain
S = Source Tab = Drain

G = Gate C = Collector
E = Emitter Tab = Collector

Features

- High Blocking Voltage
- Integrated Anti-parallel Diode
- International Standard Packages
- Low Conduction Losses

Advantages

- Low Gate Drive Requirement
- High Power Density

Applications

- Switched-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- Laser Generator
- Capacitor Discharge Circuit
- AC Switches

Symbol	Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{CES}	$I_C = 250\mu A$, $V_{CE} = V_{GE}$	2500		V
$V_{GE(th)}$	$I_C = 250\mu A$, $V_{CE} = V_{GE}$	3.0		5.5 V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}$, $V_{GE} = 0V$ $T_J = 125^\circ C$			10 μA 100 μA
I_{GES}	$V_{CE} = 0V$, $V_{GE} = \pm 20V$			± 100 nA
$V_{CE(sat)}$	$I_C = 2A$, $V_{GE} = 15V$, Note 1 $T_J = 125^\circ C$	3.15		V
		4.08		V

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values			
		Min.	Typ.	Max.	
g_{fs}	$I_C = 2\text{A}, V_{CE} = 10\text{V}$, Note 1	0.85	1.40	S	
C_{ies}	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		145	pF	
C_{oes}			8.7	pF	
C_{res}			3.2	pF	
Q_g	$I_C = 2\text{A}, V_{GE} = 15\text{V}, V_{CE} = 1\text{kV}$		10.6	nC	
Q_{ge}			0.8	nC	
Q_{gc}			6.2	nC	
$t_{d(on)}$	Resistive Switching times, $T_J = 25^\circ\text{C}$ $I_C = 2\text{A}, V_{GE} = 15\text{V}$		30	ns	
t_r			180	ns	
$t_{d(off)}$		$V_{CE} = 2\text{kV}, R_G = 47\Omega$		70	ns
t_f				182	ns
$t_{d(on)}$	Resistive Switching times, $T_J = 125^\circ\text{C}$ $I_C = 2\text{A}, V_{GE} = 15\text{V}$		30	ns	
t_r			280	ns	
$t_{d(off)}$		$V_{CE} = 2\text{kV}, R_G = 47\Omega$		74	ns
t_f				178	ns
R_{thJC}				3.90 $^\circ\text{C/W}$	
R_{thCS}		0.21		$^\circ\text{C/W}$	

Reverse Diode

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
V_F	$I_F = 2\text{A}, V_{GE} = 0\text{V}$, Note 1			2.4 V
t_{rr}	$I_F = 2\text{A}, V_{GE} = 0\text{V}, -di_f/dt = 100\text{A}/\mu\text{s}$		0.92	μs
I_{RM}			9.80	A
Q_{RM}		$V_R = 100\text{V}, V_{GE} = 0\text{V}$		4.50

Note 1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.

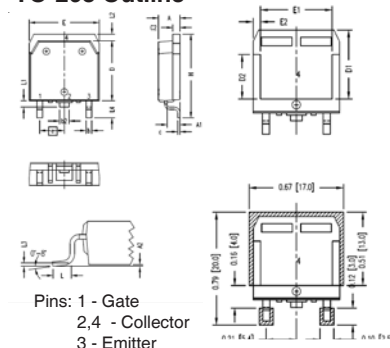
PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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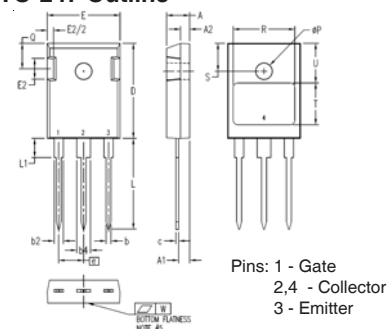
IXYS MOSFETs and IGBTs are covered 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338 B2
by one or more of the following U.S. patents: 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2
4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

TO-268 Outline



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
D2	.320	.335	8.13	8.50
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
E2	.045	.055	1.14	1.39
e	.215	BSC	5.45	BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010	BSC	0.25	BSC
L4	.150	.161	3.80	4.10

TO-247 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.087	.100	2.21	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b2	.075	.085	1.91	2.16
b4	.115	.126	2.92	3.20
c	.023	.033	0.58	0.84
D	.820	.840	20.83	21.34
E	.620	.635	15.75	16.13
E2	.175	.195	4.44	4.95
e	.215	BSC	5.45	BSC
L	.780	.810	19.81	20.57
L1	.160	.177	4.06	4.50
Q	.220	.240	5.59	6.10
R	.520	.540	13.21	13.72
S	.242	BSC	6.15	BSC
T	.355	.375	9.02	9.53
U	.345	.370	8.76	9.40
ØP	.140	.144	3.55	3.66
W	.000	.004	0.00	0.10

Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

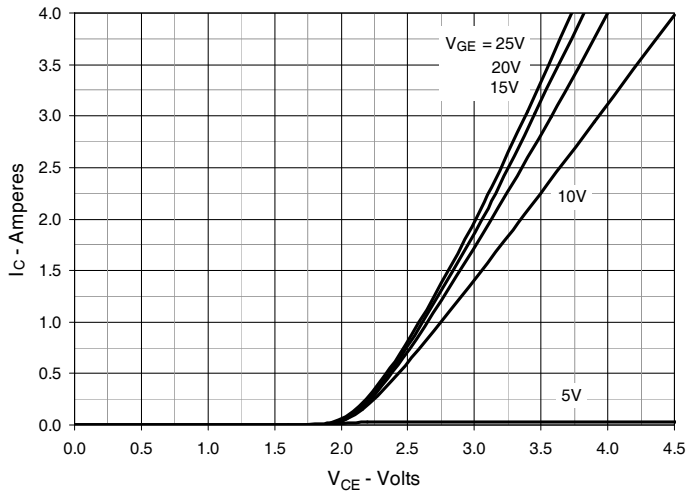


Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

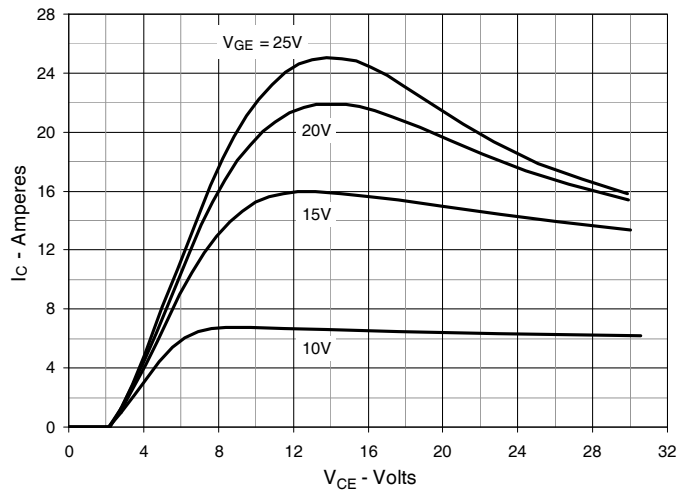


Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

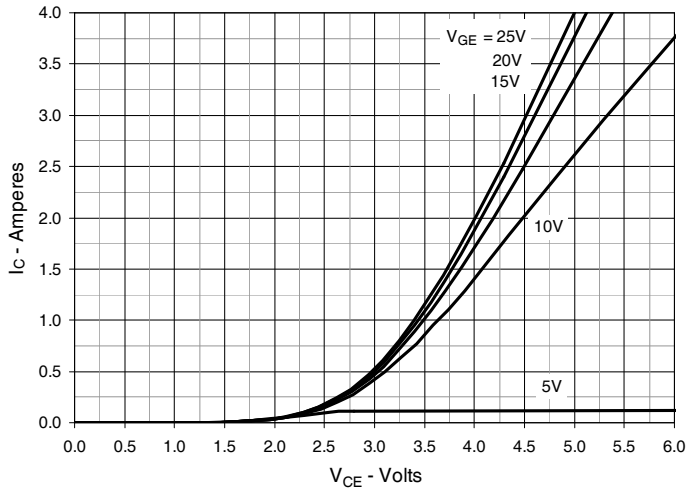


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

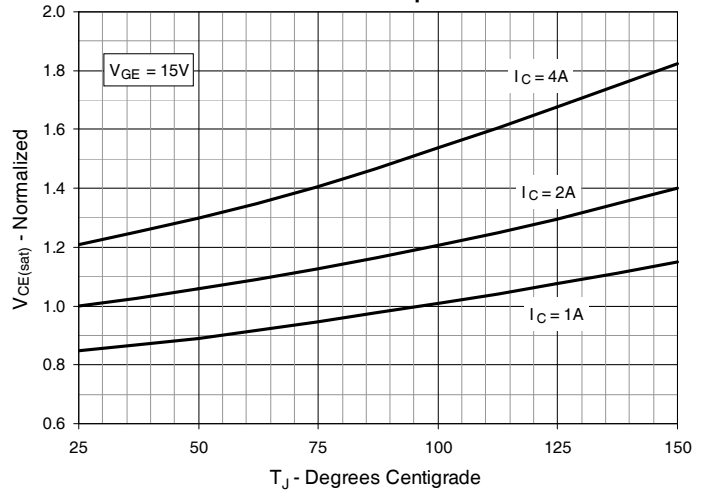


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

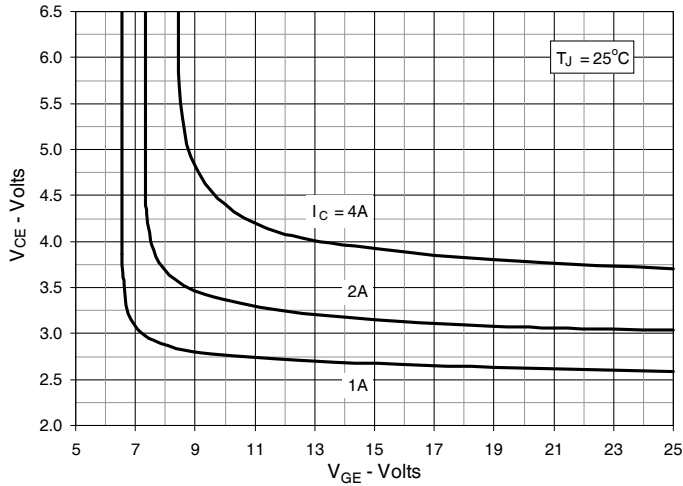


Fig. 6. Input Admittance

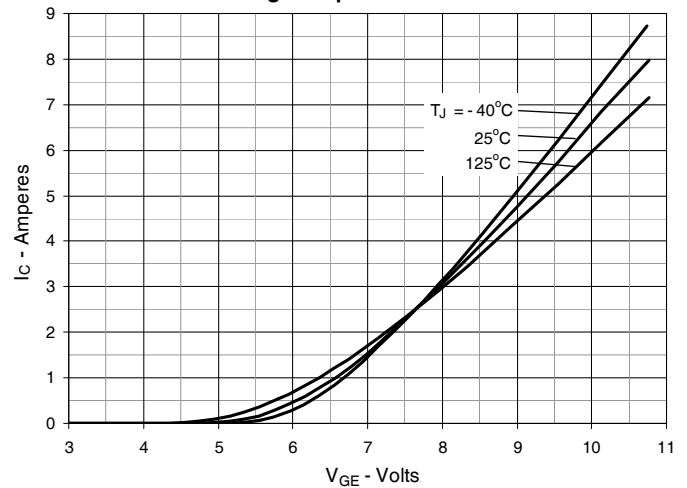


Fig. 7. Transconductance

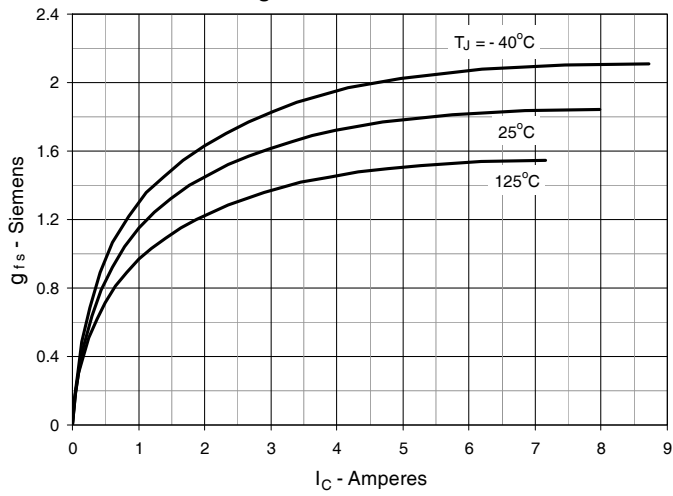


Fig. 8. Forward Voltage Drop of Intrinsic Diode

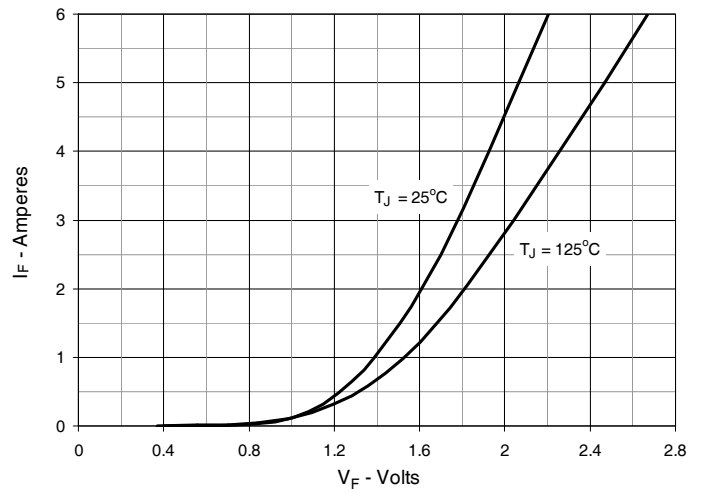


Fig. 9. Gate Charge

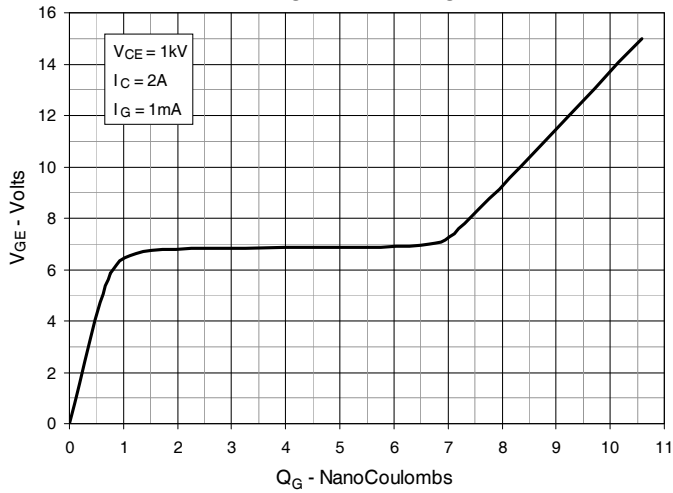


Fig. 10. Capacitance

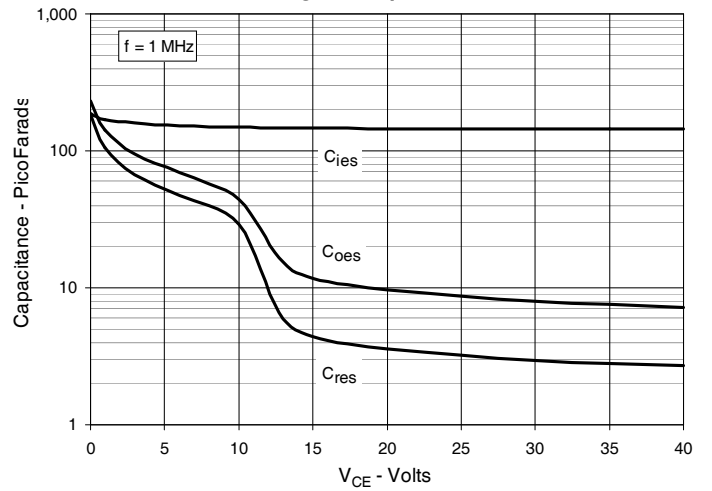


Fig. 11. Reverse-Bias Safe Operating Area

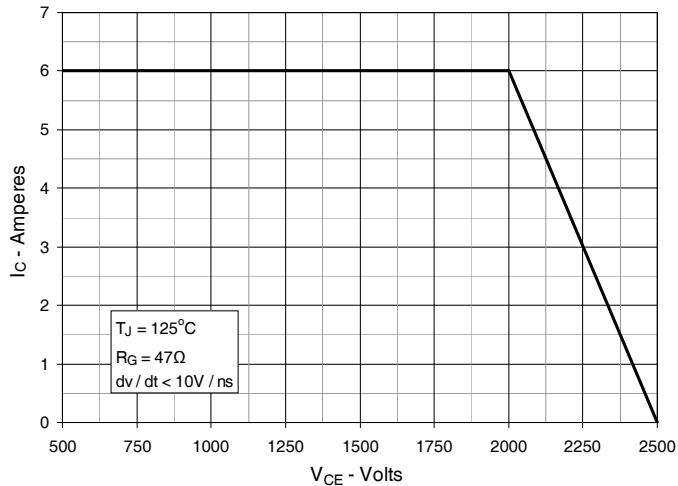


Fig. 12. Maximum Transient Thermal Impedance

